

REMARKS

Claims 1-32 are pending in this application. Claims 1-7 and 19-26 stand rejected and claims 8-18 have been withdrawn from consideration. By this Amendment, claims 2-7 have been amended and new claims 27-32 have been added. No new matter has been added. The amendments made to the claims do not alter the scope of these claims, nor have these amendments been made to define over the prior art. Rather, the amendments to the claims have been made to improve the form thereof. In light of the amendments and remarks set forth below, Applicants respectfully submit that each of the pending claims is in immediate condition for allowance.

Each of the independent claims 19 and 23 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Carey (U.S. Patent No. 5,219,787). Applicants respectfully disagree with this rejection. In particular, the Office Action relies upon the teaching in column, lines 50-67 and column, lines 1-10 of Carey.

In the cited portion of Carey, it is disclosed that the techniques taught by Carey are applicable to various kinds of substrates as well as various kinds of channels and vias. However, Carey neither teaches nor suggest that a semiconductor chip is joined to a support member prior to forming a wiring layer and an electrical contact and then peeled from the support member after forming the wiring layer and the electrical contact, as recited in claim 19 or that a build-up multilayer substrate is formed directly on a insulating layer of a semiconductor chip after forming a wiring layer and an electrical contact on the semiconductor chip as recited in claim 23.

Carey merely teaches how to form channels and vias on a substrate. Carey has no disclosure of a support member or a build-up of a multilayer substrate.

Therefore, Applicants respectfully submit that the Office Action has engaged in hindsight reconstruction using the present invention as a roadmap. As such,

Applicants respectfully submit that the pending claims are allowable over Carey and that the rejection under Carey should be withdrawn.

Applicants have responded to all of the rejections and objections recited in the Office Action. Reconsideration and a Notice of Allowance for all of the pending claims are therefore respectfully requested.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

If the Examiner believes an interview would be of assistance, the Examiner is welcome to contact the undersigned at the number listed below.

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Respectfully submitted,

By

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